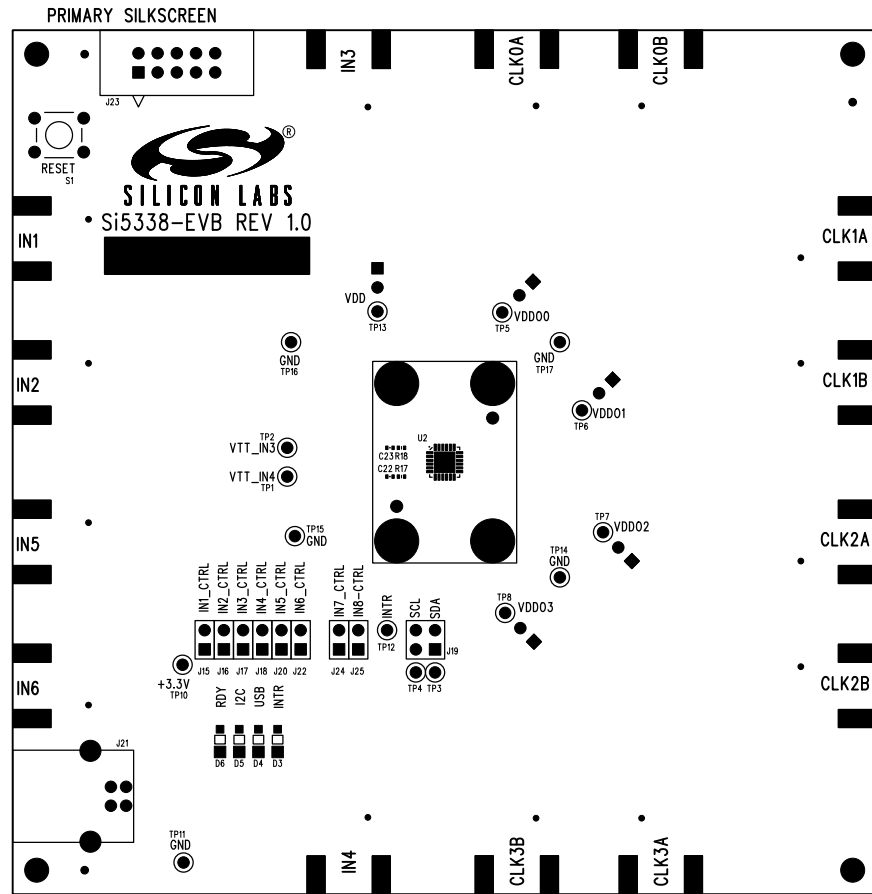
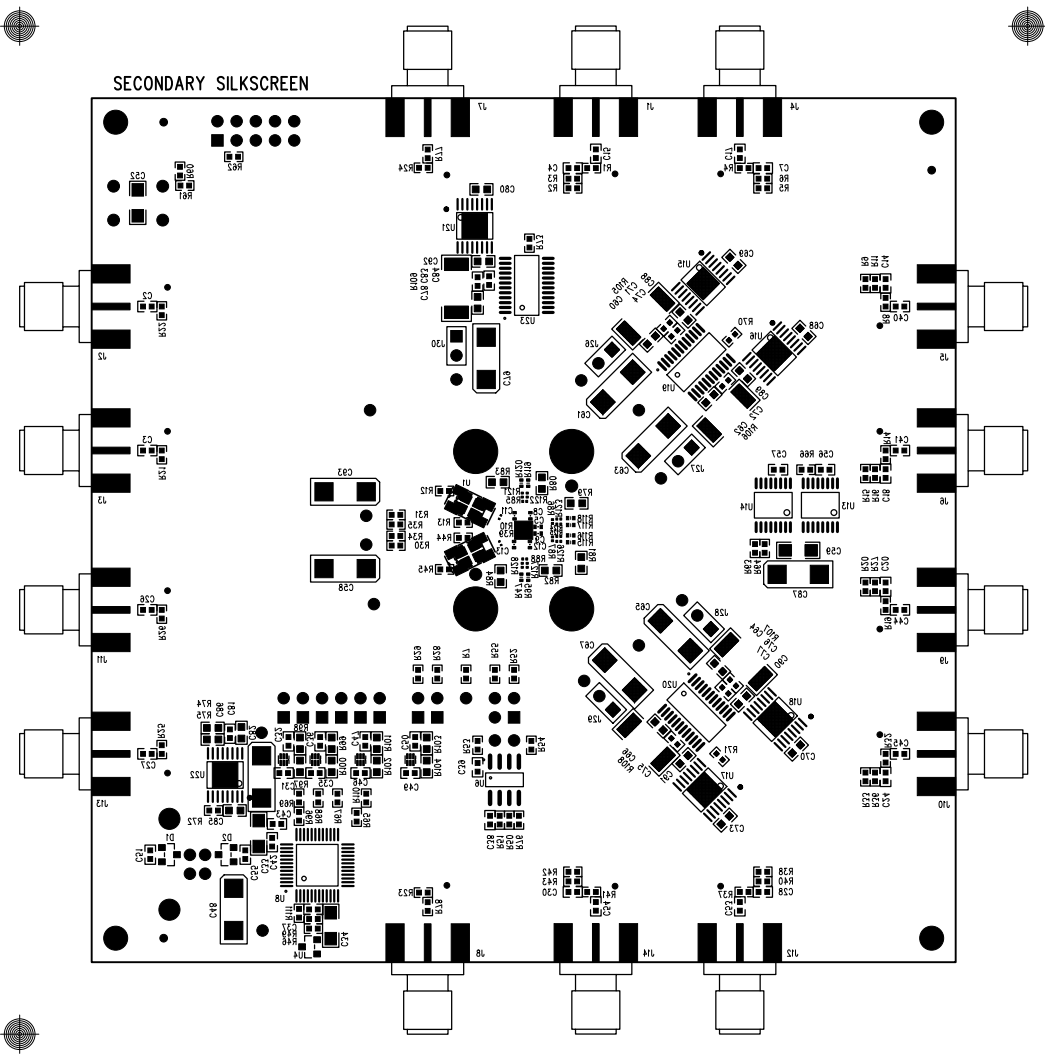
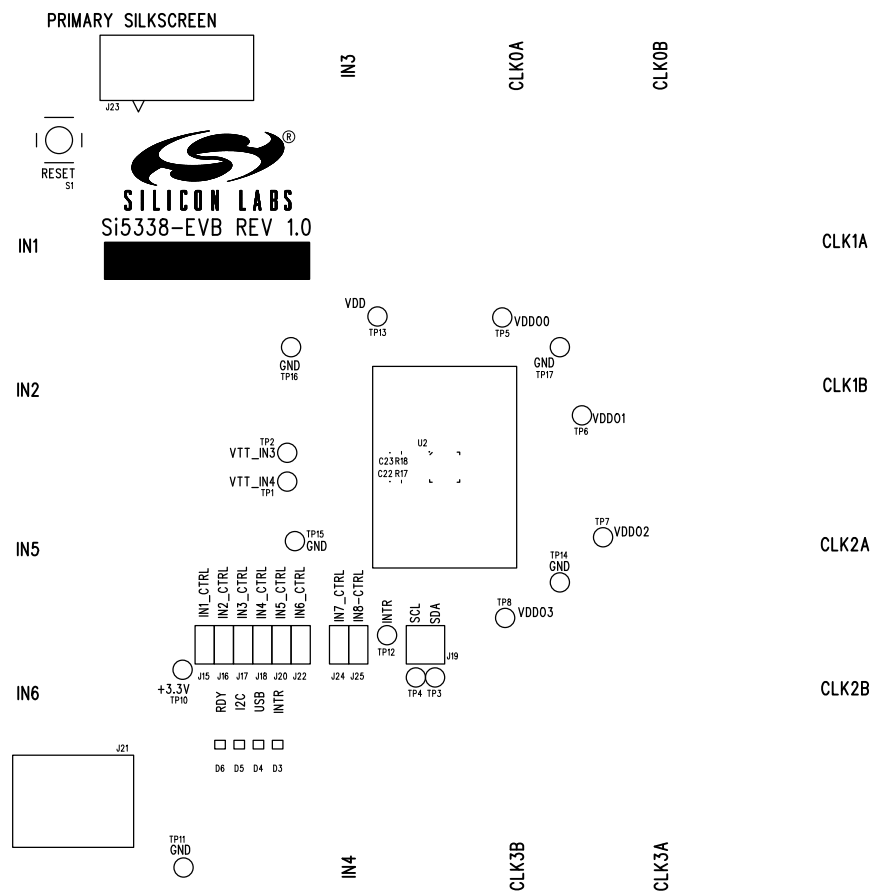


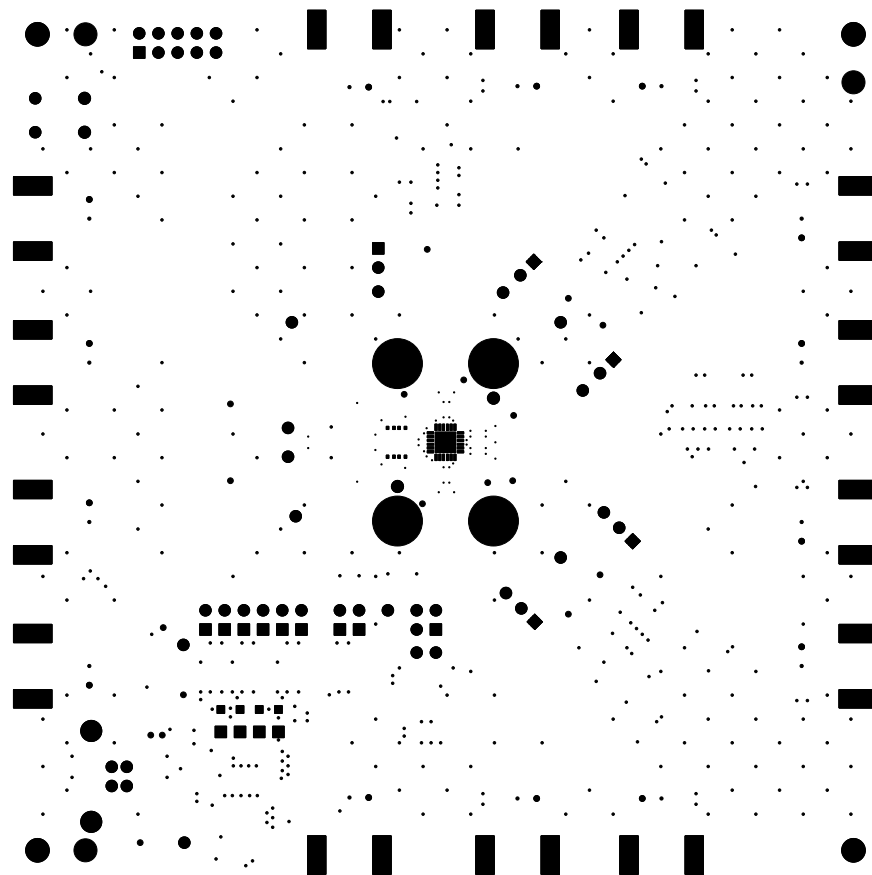




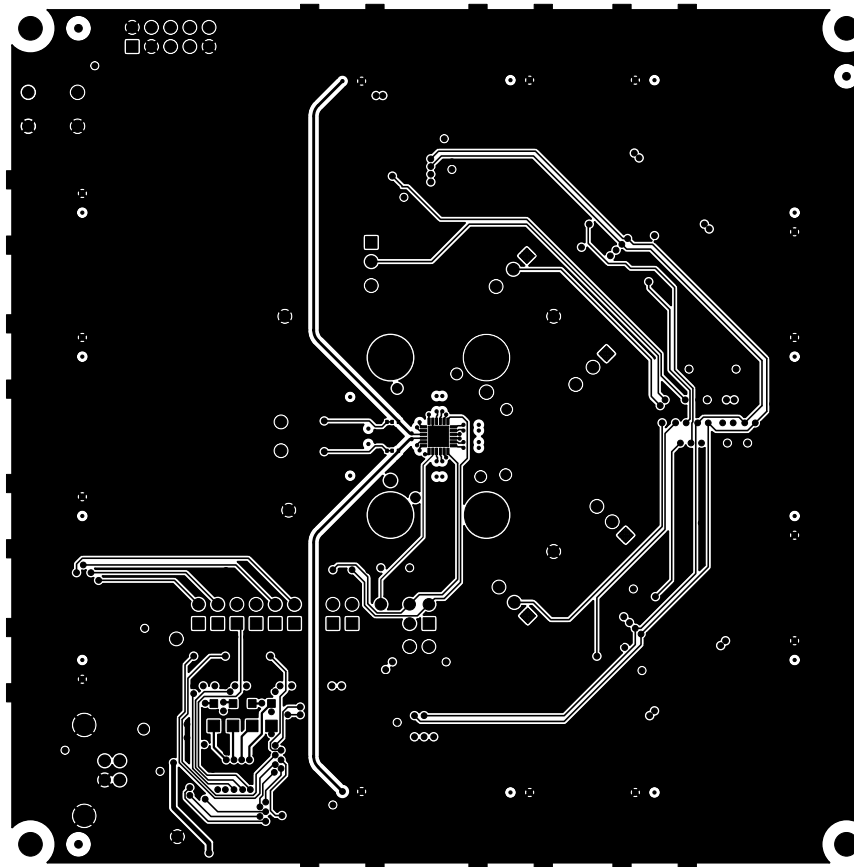




PRIMARY SOLDER MASK

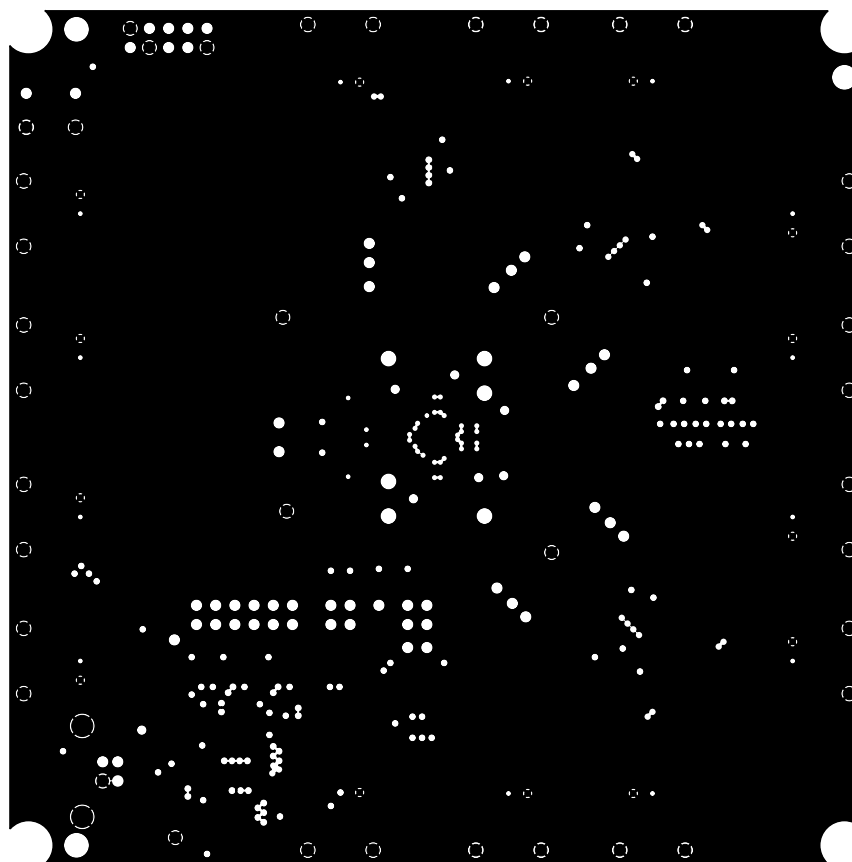


PRIMARY SIDE



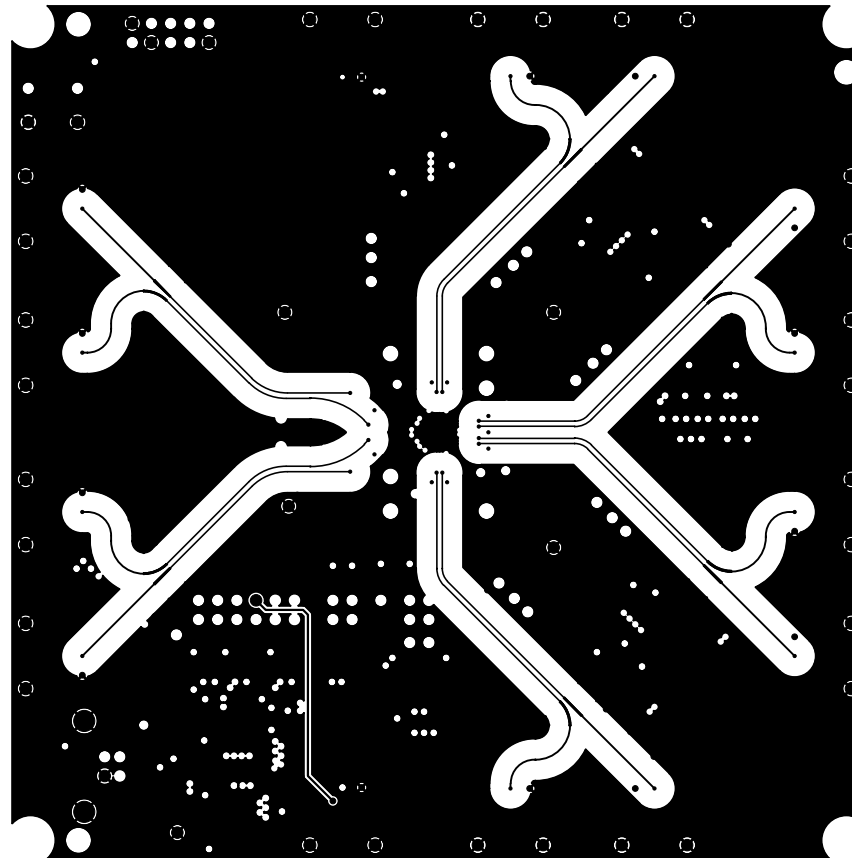


L02



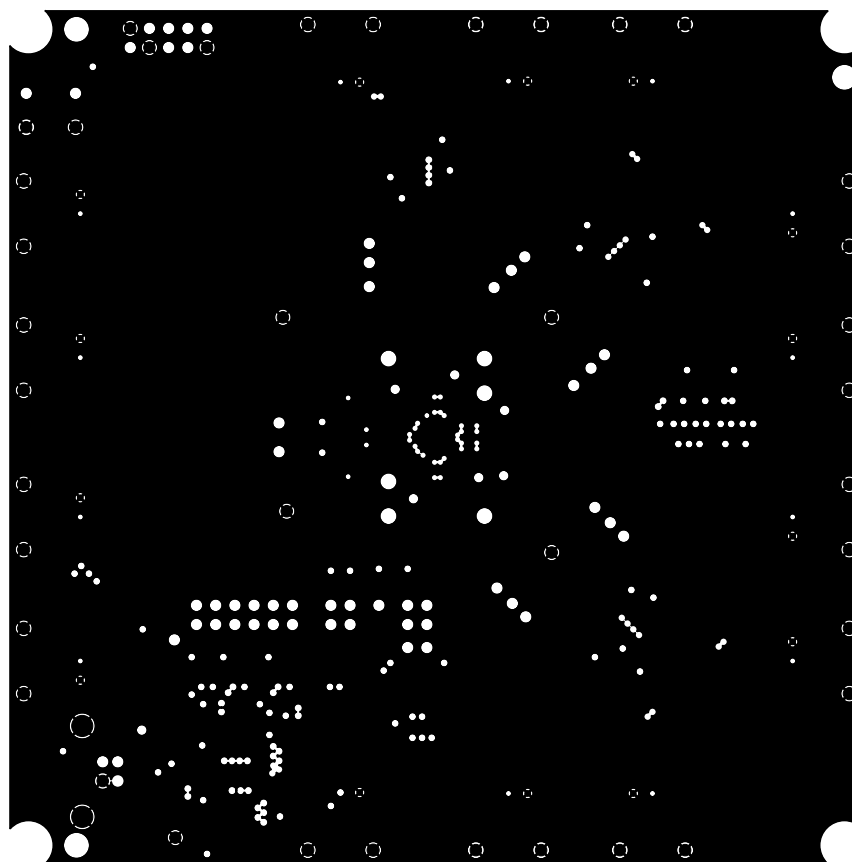


L03



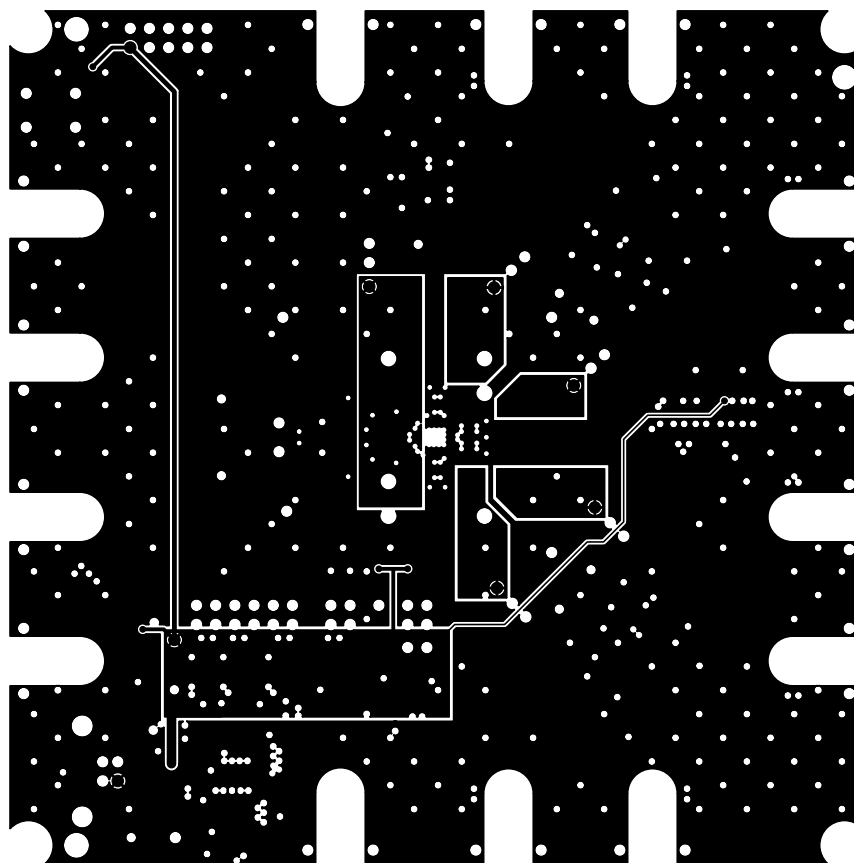


L04

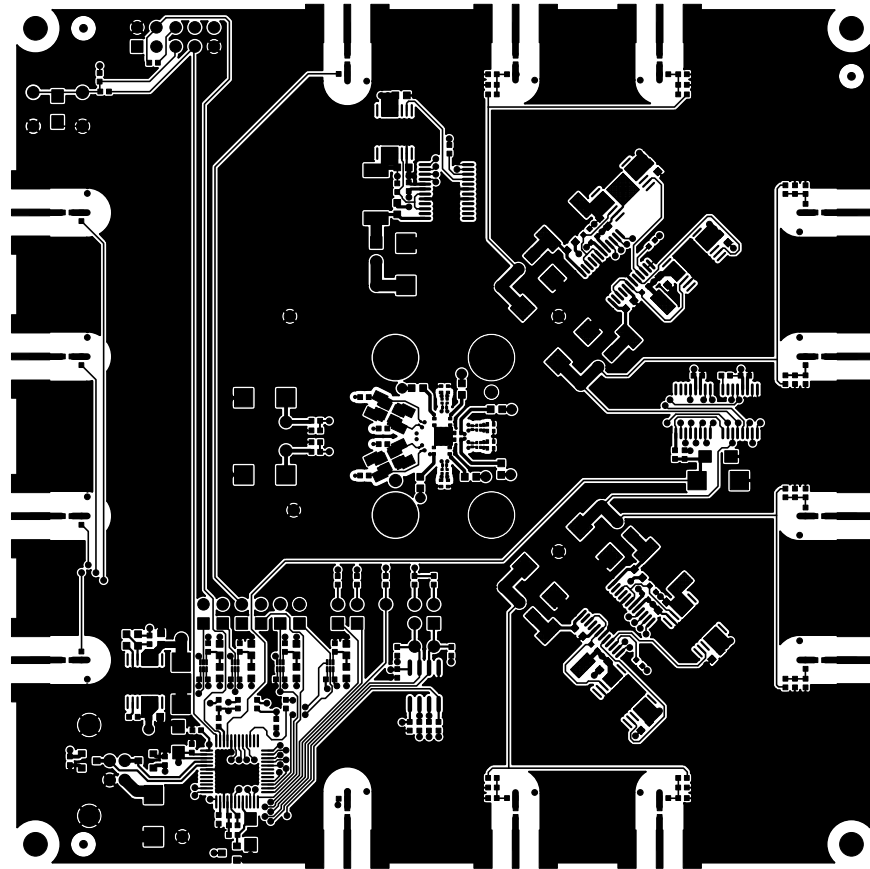




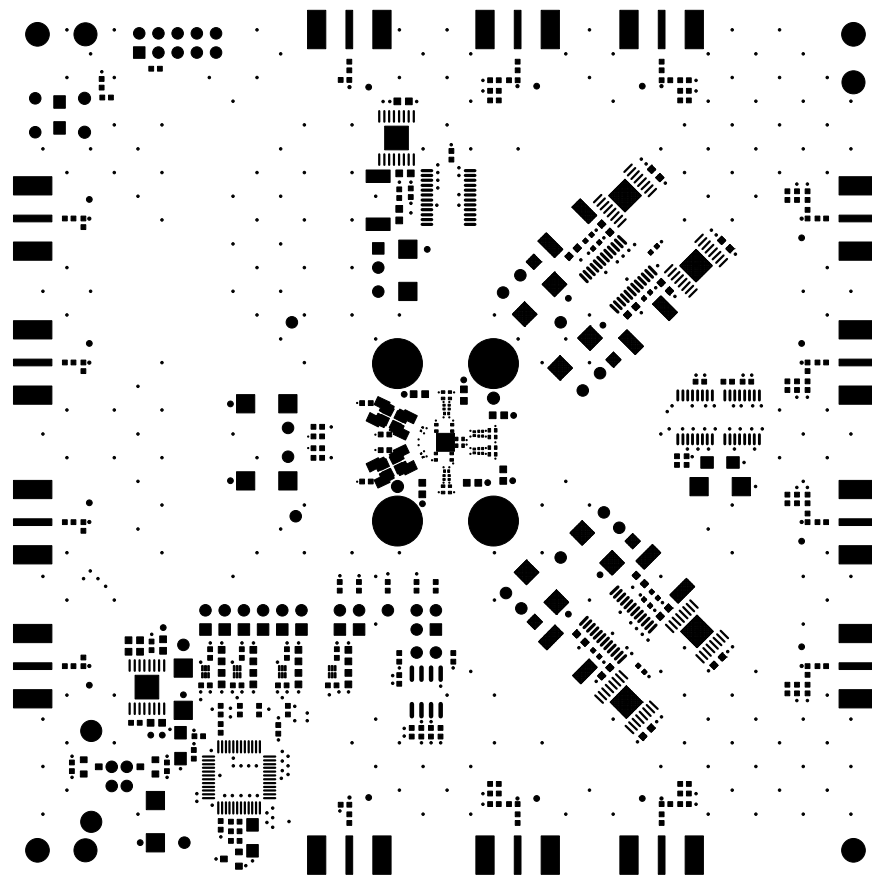
L05



SECONDARY SIDE

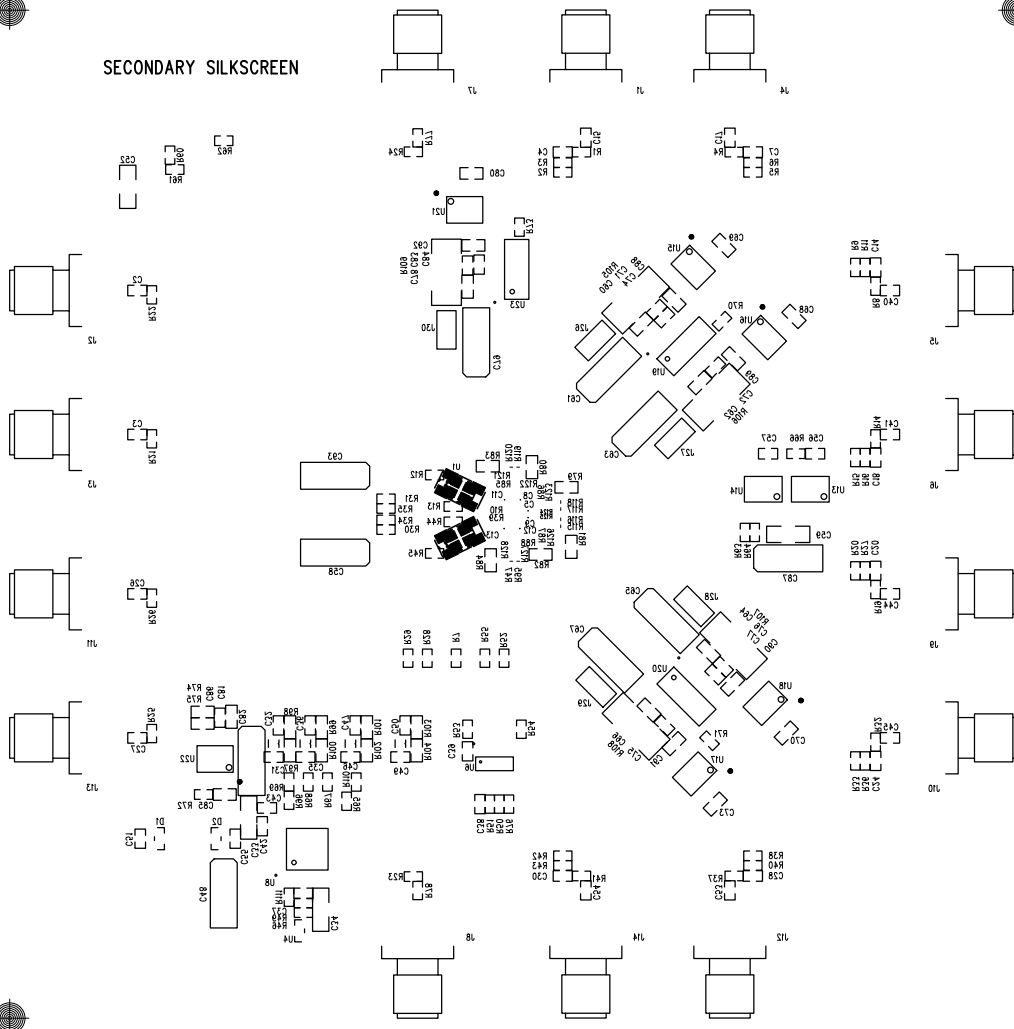


SECONDARY SOLDER MASK





SECONDARY SILKSCREEN



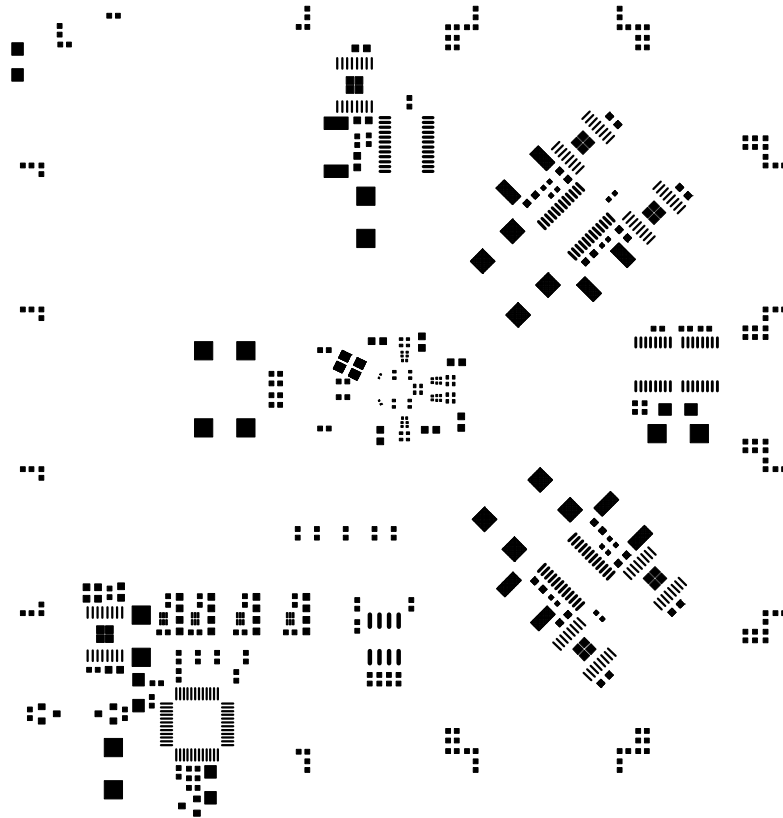


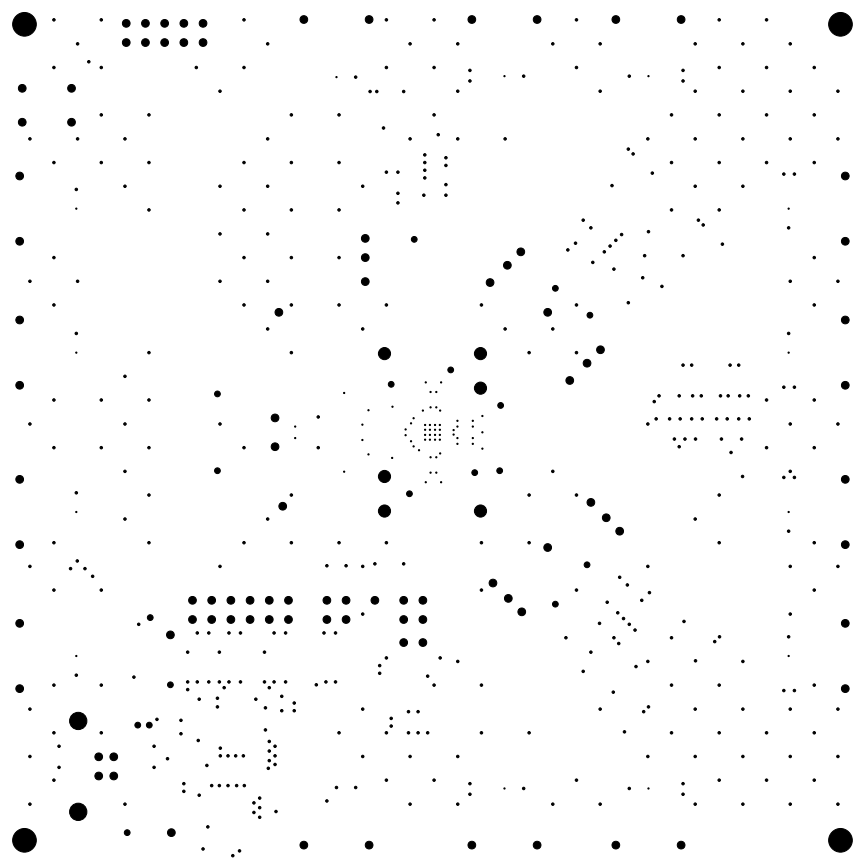
PRIMARY SOLDER PASTE

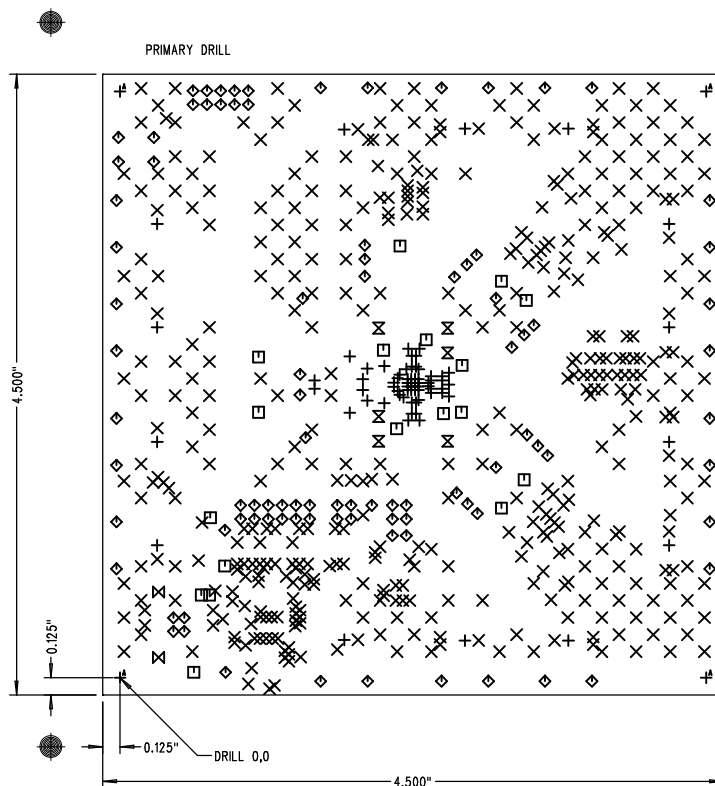




SECONDARY SOLDER PASTE







NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. MATERIAL SHALL BE COPPER CLAD FR-4, NEMA GRADE PER IPC-4101, COLOR NATURAL.
4. COPPER WEIGHT SHALL BE 0.5 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE ± 0.003 ".
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE PER STACKUP DETAIL $\pm 10\%$.
10. WARP/TWIST SHALL NOT EXCEED 1.0%.
11. FINISH SHALL BE LPI, GREEN SMOBC, SOLDERABLE SURFACES ARE TO BE ENIG.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. REFERENCE ADDITIONAL FAB NOTES IN FILE README.TXT

BY REF. LAYER SPECIFIED DIMENSIONS WITHOUT APPROVAL FROM SILICON LABS.							
SEMI- FILENAME	LAYER	SINGLE ENDS APPEARANCE (DRM)	DIFFERENTIAL APPEARANCE (DNC)	SPACE APPEARANCE (DNC)	TRACE APPEARANCE (DNC)	THICKNESS (DNC)	THICKNESS (DNC)

533x3xVB_P05.PHD PRIMARY SILKSCREEN

533x3xVB_P06.PHD PRIMARY SOLDER MASK

533x3xVB_P06.PHD	L01	PRIMARY (Solder)	10	10	100	0.001	0.5 oz.
533x3xVB_L02.PHD	L01	PLANE (Solder)	10	10	100	0.001	0.5 oz.
533x3xVB_L03.PHD	L01	PLANE (Solder)	10	10	100	0.001	0.5 oz.
533x3xVB_L04.PHD	L01	PLANE (Solder)	10	10	100	0.001	0.5 oz.
533x3xVB_L05.PHD	L01	PLANE (Solder)	10	10	100	0.001	0.5 oz.
533x3xVB_S06.PHD	L06	SECONDARY (Solder)	10	10	100	0.001	0.5 oz.

533x3xVB_S06.PHD SECONDARY SOLDER MASK

533x3xVB_S07.PHD SECONDARY SILKSCREEN

SIZE	QTY	SYM	PLTD	TOOL	TOL
0.008	74	+	P	1	+0/-0.008
0.015	441	X	P	2	+0/-0.015
0.030	18	□	P	3	+/-0.003
0.040	92	◇	P	4	+/-0.003
0.063	6	⊗	NP	5	+/-0.003
0.091	2	⊗	P	6	+/-0.003
0.125	4	A	NP	7	+/-0.003

UNLESS OTHERWISE SPECIFIED			THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SHALL NOT BE DUPLICATED OR USED FOR ANY PURPOSE OTHER THAN THAT FOR WHICH PROVIDED OR DISCLOSED IN WHOLE OR IN PART, WITHOUT THE WRITTEN CONSENT OF SILICON LABORATORIES, INC.		COMPANY:  400 W CESAR CHAVEZ AUSTIN, TX 78701 (512)416-8500 www.silabs.com	
DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH DIMENSIONS IN BRACKETS () ARE IN MILLIMETERS INTERPRET DRAWING PER MIL-D-1000					NAME: Si533xCEVB	
TOLERANCES					REV: 1.0	
HOLE TOLERANCES PER 78027						
DECIMALS	ANGLES	SURFACES	DESIGN	DG	080CT2008	SIZE X
.XX +/-	+/-	MICROMETERS	LAYOUT	CT	080CT2008	PART NUMBER:
.XXX +/-						
PART TO BE FREE OF BURRS			DO NOT SCALE DRAWING		SCALE 1:1 FABRICATION DRAWING SHEET 1 OF 1	
BREAK EDGES	BEND RADII	BEND RELIEF				
MAX	MAX	MAX				